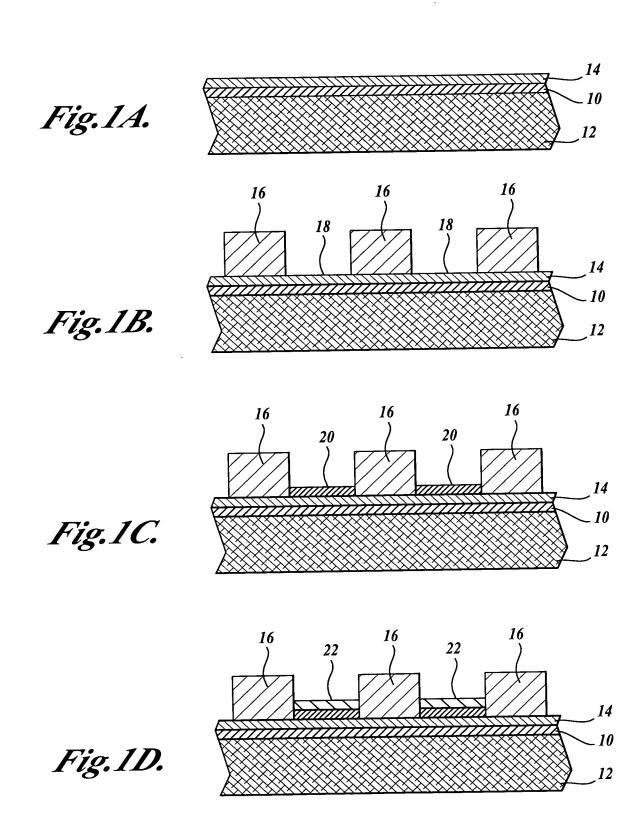
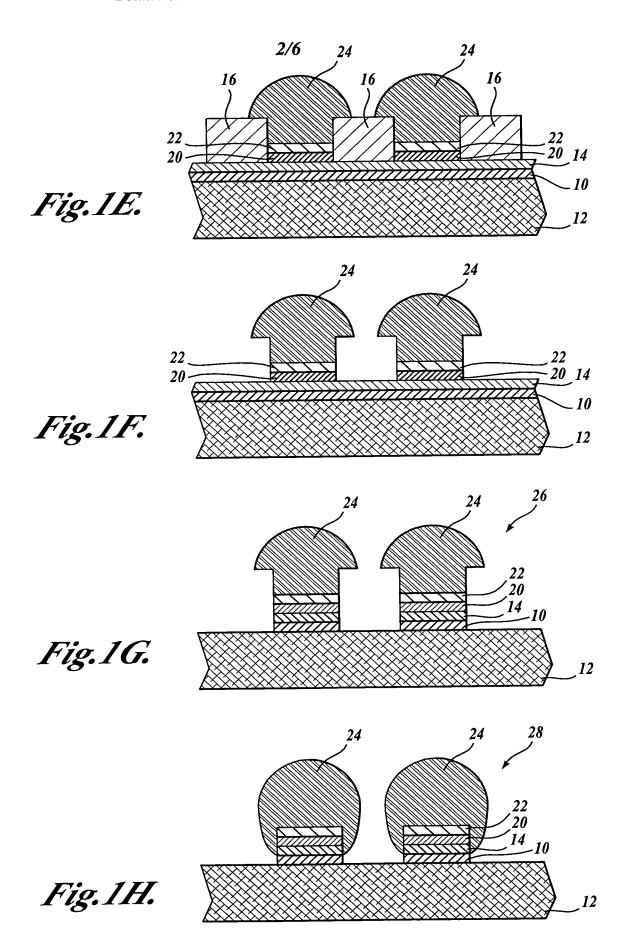
ALLOY SOLDER PRECURSORS
Inventor: Bioh Kim
Docket No.: SEMT116964

1/6



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Title: PROCESSES AND TOOLS FOR FORMING LEAD-FREE ALLOY SOLDER PRECURSORS

Inventor: Bioh Kim
Docket No.: SEMT116964

3/6 FORMING UNDER BUMP METALLURGY (UBM) ON SUBSTRATE FORMING PATTERNED MASK OVER UBM FORMING DIFFUSION BARRIER LAYER OVER THE EXPOSED UBM FORMING LEAD-FREE FIRST CONDUCTIVE LAYER OVER DIFFUSION BARRIER LAYER FORMING LEAD-FREE SECOND CONDUCTIVE LAYER OVER FIRST CONDUCTIVE LAYER REMOVE PATTERNED MASK REMOVE EXPOSED UBM REFLOW CONDUCTIVE LAYERS TO FORM ALLOYED FEATURE

Fig.2.

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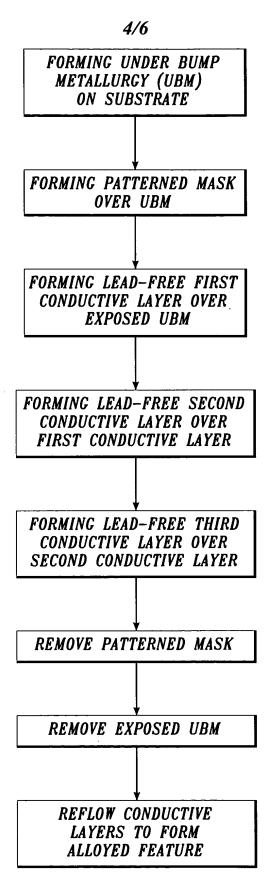


Fig.3.

ALLOY SOLDER PRECURSORS Inventor: Bioh Kim
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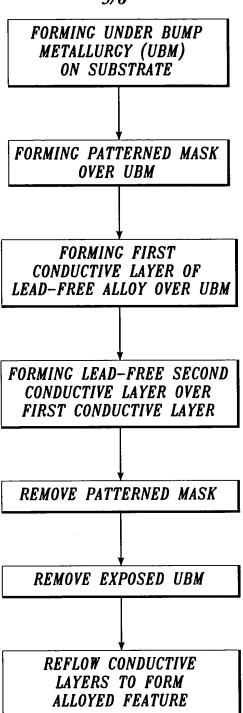


Fig.4.

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6/6

